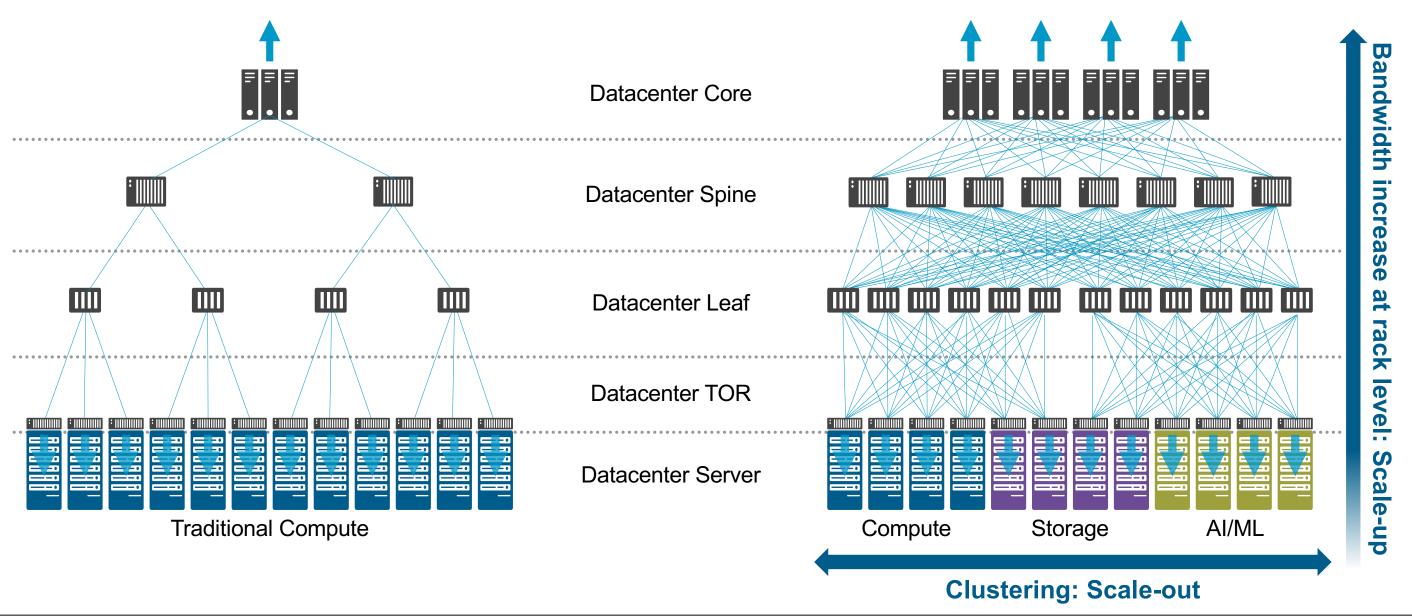


Optical Systems Division (OSD)

November 2021



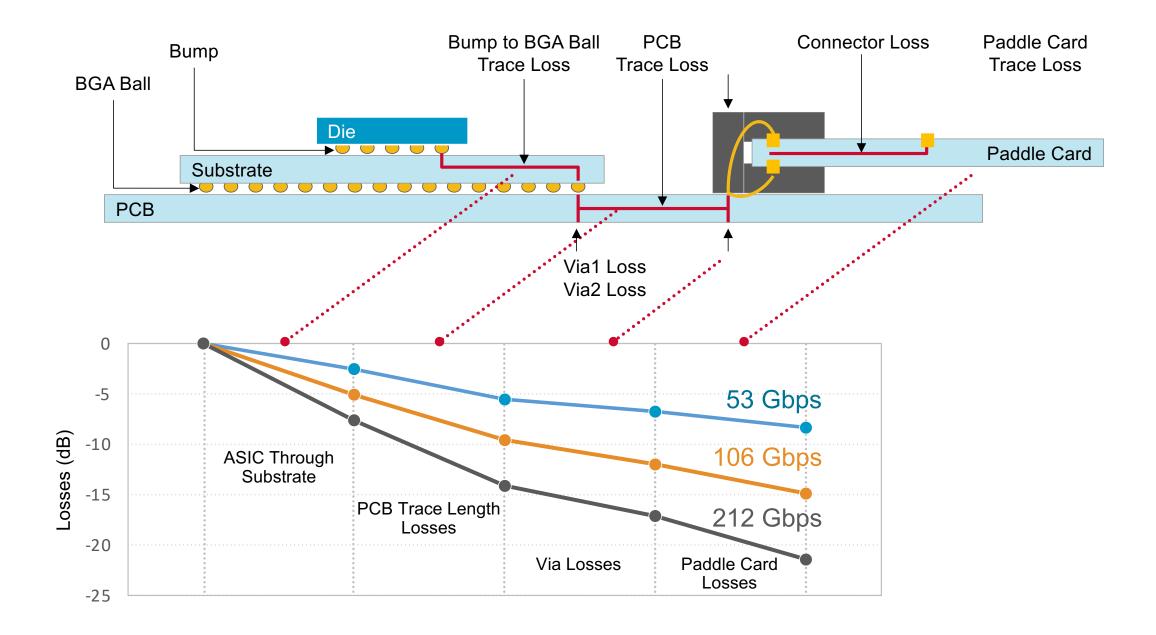
As data centers scale-out and scale-up.....



Resource utilization drives resource pooling and new connectivity and data movement paradigms

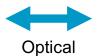


...and copper I/O approaches a reach limit...





...optical connectivity enables new architectures





Standard TOR

Compute











Clusters w/Standard TOR







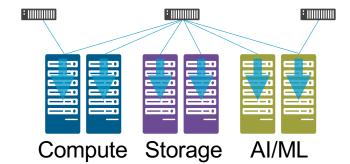


TOR Collapse

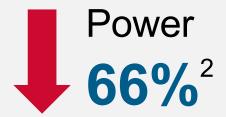




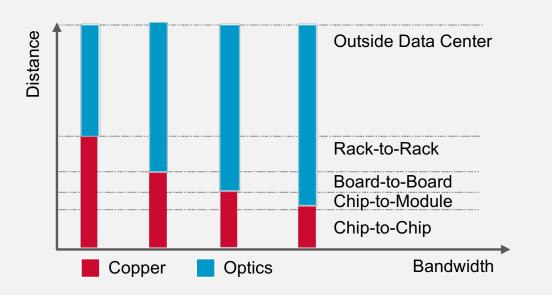
TOR Collapse with Redundancy











- 1. Internal Broadcom estimate
- 2. https://www.youtube.com/watch?v=w1J9SW62ZnI

Expansion of east-west connectivity drives a transition from copper to optical

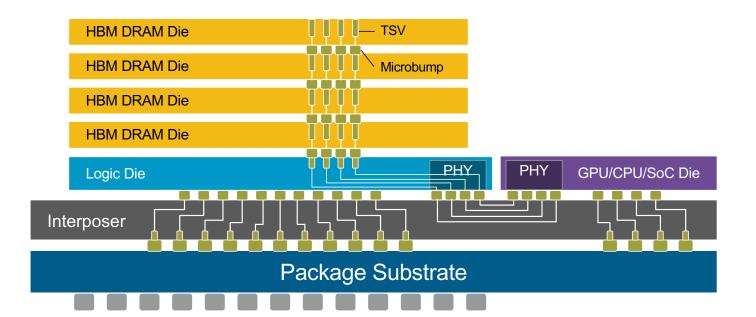
Introducing SCIP: Silicon Photonics Chiplets In Package

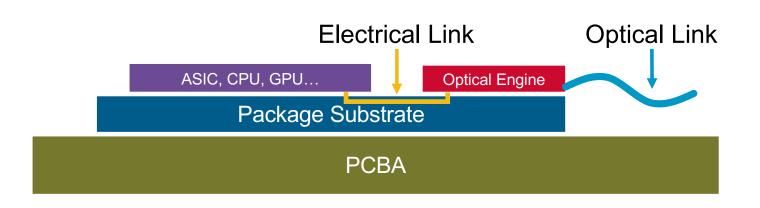
Co-Packaging

- Integration of multiple dies
 on a common package substrate
- High volume use cases today like HBM

SCIP: Co-Packaged Optics

- Integration of optical engines
 on a common package substrate
- Objective: alleviate the "interconnect density bottleneck"



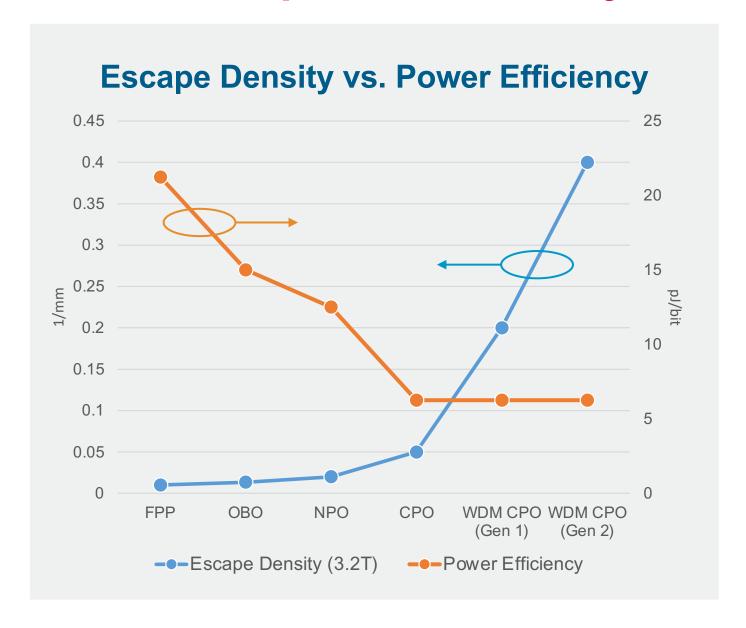


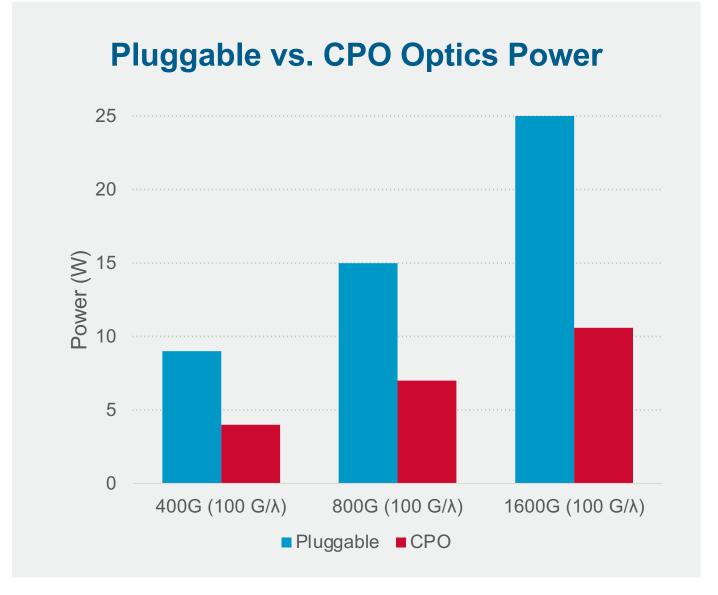


^{*} Source: Image, AMD, https://www.amd.com/en/technologies/hbm

^{*} Source: Yole Developpement, http://www.yole.fr/3D_25D_Stacking_Technologies_IntelEMIB.aspx#.YJyx7pNKh25

SCIP offers power efficiency and bandwidth density benefits

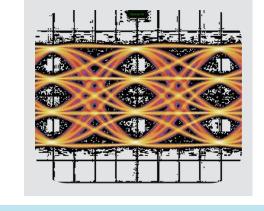


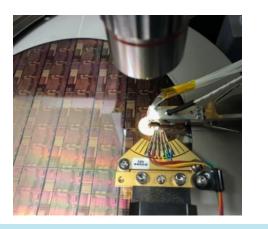


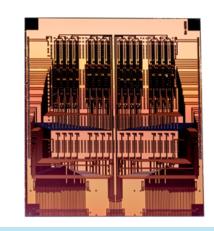


SCIP: The latest semiconductor innovation from Broadcom









ASIC

SerDes and DSP

in leading node

Core switch,

Sustained

generational

differentiation

 Power and performance

Mixed Signal

optimized in both SiGe and CMOS

IC

Optical Devices & Fabs

- 50M lasers/year from internal fabs
- High-volume optical manufacturing
- High-power, multi-wavelength sources

Advanced **Packaging & Test**

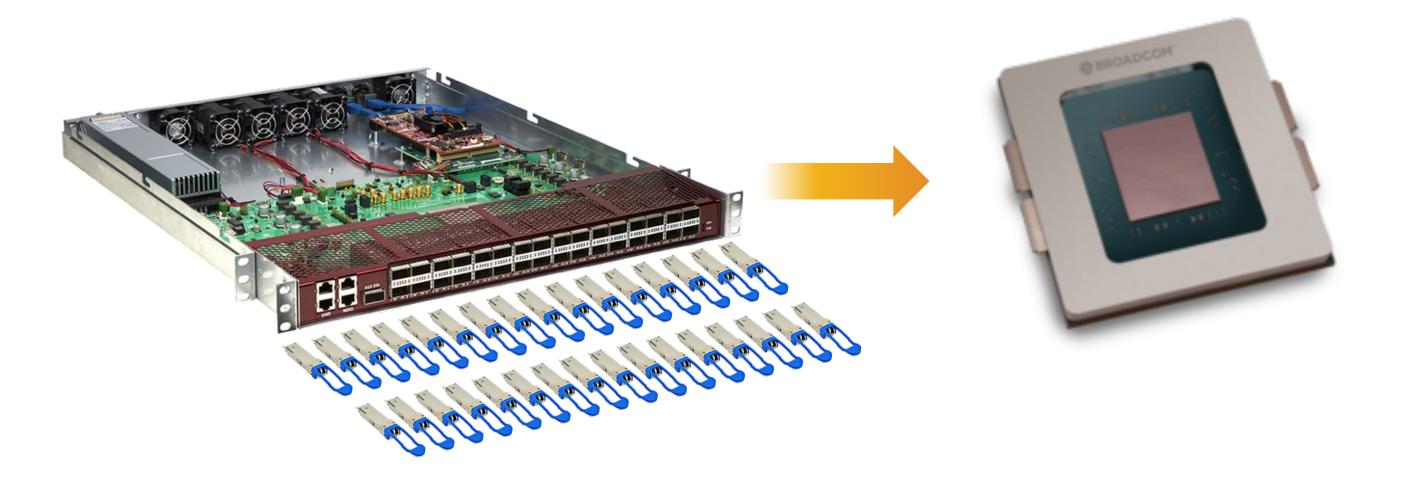
- Wafer-level test
- TSV
- 2.5D/3D integration

Silicon **Photonics**

- High-density PIC design
- Modulators and PDs in silicon
- Low-loss SOI waveguides



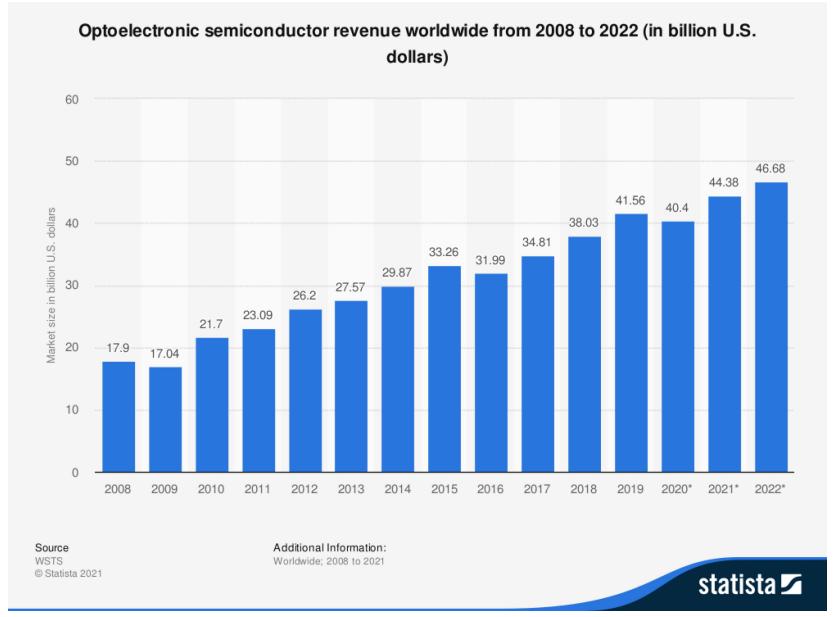
Visualize the SCIP Benefit



Simplifying next generation systems



SCIP: A new era of integrated connectivity begins







Source: Statista 2021

- Markets and Markets, Silicon Photonics Market with COVID-19 Impact Analysis by Product
- 2. Emgen Research



